

Title (en)  
ASSEMBLY COMPRISING A SEMICONDUCTOR CHIP AND SUPPORT THEREFOR, IN ADDITION TO METHOD FOR A BONDED WIRING CONNECTION

Title (de)  
ANORDNUNG MIT EINEM HALBLEITERCHIP UND DESSEN TRÄGER SOWIE VERFAHREN ZUR BOND-DRAHTVERBINDUNG

Title (fr)  
CIRCUIT COMPRENANT UNE PUCE SEMI-CONDUCTRICE ET SON SUPPORT ET PROCEDE DE LIAISON PAR FIL DE CONNEXION

Publication  
**EP 1523769 A1 20050420 (DE)**

Application  
**EP 03787714 A 20030722**

Priority  
• DE 0302465 W 20030722  
• DE 10233607 A 20020724

Abstract (en)  
[origin: DE10233607A1] A semiconductor chip (3) is connected to a carrier (1) by a wire (6) which has nail head end contacts (4,5). The carrier has a wedge contact (7) to the wire nail head and forms a through connection (9). An Independent claim is also included for a process for electrically connecting a chip and carrier as above.

IPC 1-7  
**H01L 21/607**; **H01L 23/498**; **H01L 21/48**

IPC 8 full level  
**H01L 21/48** (2006.01); **H01L 21/607** (2006.01); **H01L 23/498** (2006.01)

CPC (source: EP US)  
**H01L 21/486** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/85** (2013.01 - EP US); **H05K 3/328** (2013.01 - EP US); **H05K 3/4015** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 24/78** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/48095** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48235** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2224/4848** (2013.01 - EP US); **H01L 2224/48599** (2013.01 - EP US); **H01L 2224/48699** (2013.01 - EP US); **H01L 2224/78301** (2013.01 - EP US); **H01L 2224/85051** (2013.01 - EP US); **H01L 2224/85181** (2013.01 - EP US); **H01L 2224/85205** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01027** (2013.01 - EP US); **H01L 2924/01032** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H05K 1/113** (2013.01 - EP US); **H05K 2203/049** (2013.01 - EP US)

C-Set (source: EP US)

EP

1. **H01L 2224/45124 + H01L 2924/00014**
2. **H01L 2224/85205 + H01L 2224/45124 + H01L 2924/00**
3. **H01L 2224/85205 + H01L 2224/48465 + H01L 2924/00**
4. **H01L 2224/48465 + H01L 2224/48095 + H01L 2924/00**
5. **H01L 2224/45144 + H01L 2924/00015**
6. **H01L 2224/45124 + H01L 2924/00015**
7. **H01L 2924/00014 + H01L 2224/85399**
8. **H01L 2924/00014 + H01L 2224/05599**
9. **H01L 2224/45144 + H01L 2924/00014**
10. **H01L 2224/48095 + H01L 2924/00014**
11. **H01L 2224/4848 + H01L 2224/48465**
12. **H01L 2224/78301 + H01L 2924/00014**
13. **H01L 2224/85181 + H01L 2224/48465**
14. **H01L 2224/48465 + H01L 2224/48227**
15. **H01L 2224/48465 + H01L 2224/48227 + H01L 2924/00**
16. **H01L 2224/85205 + H01L 2224/45144 + H01L 2924/00**

US

1. **H01L 2224/45124 + H01L 2924/00014**
2. **H01L 2224/85205 + H01L 2224/45124 + H01L 2924/00**
3. **H01L 2224/85205 + H01L 2224/48465 + H01L 2924/00**
4. **H01L 2224/48465 + H01L 2224/48095 + H01L 2924/00**
5. **H01L 2224/45144 + H01L 2924/00015**
6. **H01L 2224/45124 + H01L 2924/00015**
7. **H01L 2224/45144 + H01L 2924/00014**
8. **H01L 2224/48095 + H01L 2924/00014**
9. **H01L 2224/4848 + H01L 2224/48465**
10. **H01L 2224/78301 + H01L 2924/00014**
11. **H01L 2224/85181 + H01L 2224/48465**
12. **H01L 2224/48465 + H01L 2224/48227**
13. **H01L 2224/48465 + H01L 2224/48227 + H01L 2924/00**
14. **H01L 2224/85205 + H01L 2224/45144 + H01L 2924/00**

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FR IT

DOCDB simple family (publication)

**DE 10233607 A1 20040212; DE 10233607 B4 20050929;** AU 2003258458 A1 20040303; EP 1523769 A1 20050420;  
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DOCDB simple family (application)

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